



60V N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

Product Summary

BV _{DSS}	R _{DS(ON)} MAX	I _{D MAX} T _C = +25°C
60V	6.2mΩ @ V _{GS} = 10V	98A

Features

- 100% Unclamped Inductive Switching (UIS) Test in Production— Ensures More Reliable and Robust End Application
- High Conversion Efficiency
- Low R_{DS(ON)}—Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Description

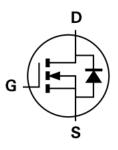
This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Synchronous Rectifier
- DC-DC Converters
- Power Management

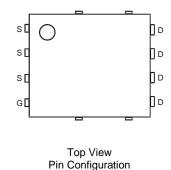
Mechanical Data

- Case: PowerDI[®]5060-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish—Matte Tin Annealed over Copper Leadframe;
 Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.097 grams (Approximate)





Internal Schematic



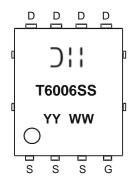
Ordering Information (Note 4)

Part Number	Case	Packaging
DMT6006SPS-13	PowerDI5060-8	2500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



The Manufacturer's Marking
T6006SS = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 19 = 2019)
WW = Week Code (01 to 53)

Document Number: DS41013 Rev. 2 - 2



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V _{DSS}	60	V	
Gate-Source Voltage	V _{GSS}	±20	V	
Ocationary Davis Oceans (Note 5) // 40/	T _A = +25°C	,	16.2	А
Continuous Drain Current (Note 5) V _{GS} = 10V	T _A = +70°C	ID	13.0	
Operation of the Comment (Alata Olivia and C	T _C = +25°C		98.0	А
Continuous Drain Current (Note 6) V _{GS} = 10V	T _C = +70°C	ID	78.4	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	390	Α	
Maximum Continuous Body Diode Forward Current (Note 6)	I _S	98	Α	
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)	I _{SM}	390	Α	
Avalanche Current, L = 0.3mH	I _{AS}	24.2	Α	
Avalanche Energy, L = 0.3mH	E _{AS}	87.9	mJ	

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	P_{D}	2.45	W
Thermal Resistance, Junction to Ambient (Note 5)		$R_{\Theta JA}$	51	°C/W
Total Power Dissipation (Note 6)	T _C = +25°C	P _D	89.3	W
Thermal Resistance, Junction to Case (Note 6)		Rejc	1.4	°C/W
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C

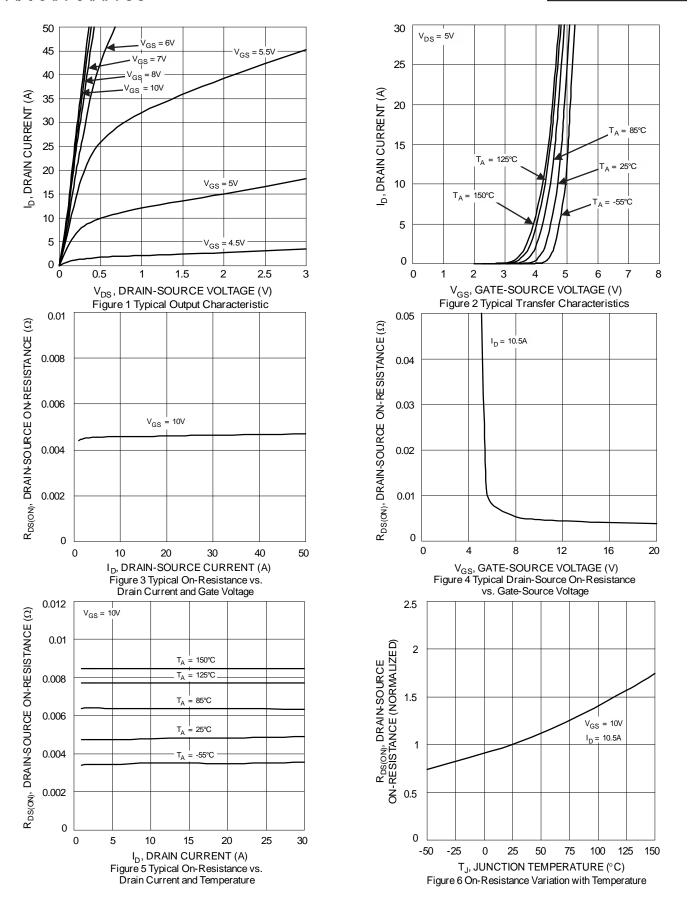
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	60	_	_	V	$V_{GS} = 0V, I_D = 1mA$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	V _{DS} = 48V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	2	_	4	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	ı	4.8	6.2	mΩ	$V_{GS} = 10V, I_D = 10.5A$	
Diode Forward Voltage	V_{SD}	_	0.8	1.2	V	$V_{GS} = 0V, I_{S} = 21A$	
DYNAMIC CHARACTERISTICS (Note 8)						·	
Input Capacitance	Ciss		1721			$V_{DS} = 30V$, $V_{GS} = 0V$, $f = 1MHz$	
Output Capacitance	Coss	1	740	1	pF		
Reverse Transfer Capacitance	Crss	_	49	_			
Gate Resistance	R_g	_	0.6	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Q_g	_	27.9	_			
Gate-Source Charge	Qgs	_	7.4	_	nC	$V_{DS} = 30V$, $I_D = 21A$, $V_{GS} = 10V$	
Gate-Drain Charge	Q_{gd}	_	7.3	_			
Turn-On Delay Time	t _{D(ON)}	_	7.5	_			
Turn-On Rise Time	t _R	_	8.2	_		$V_{DD} = 30V, V_{GS} = 10V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	16.5	_	ns	$I_D = 10.5A, R_g = 4.7\Omega$	
Turn-Off Fall Time	t _F	_	9.8	_			
Reverse Recovery Time	t _{RR}	_	37.0	_	ns	L 04.4 di/di 000.4/c	
Reverse Recovery Charge	Q _{RR}	_	42.9	_	nC	I _F = 21A, di/dt = 300A/μs	

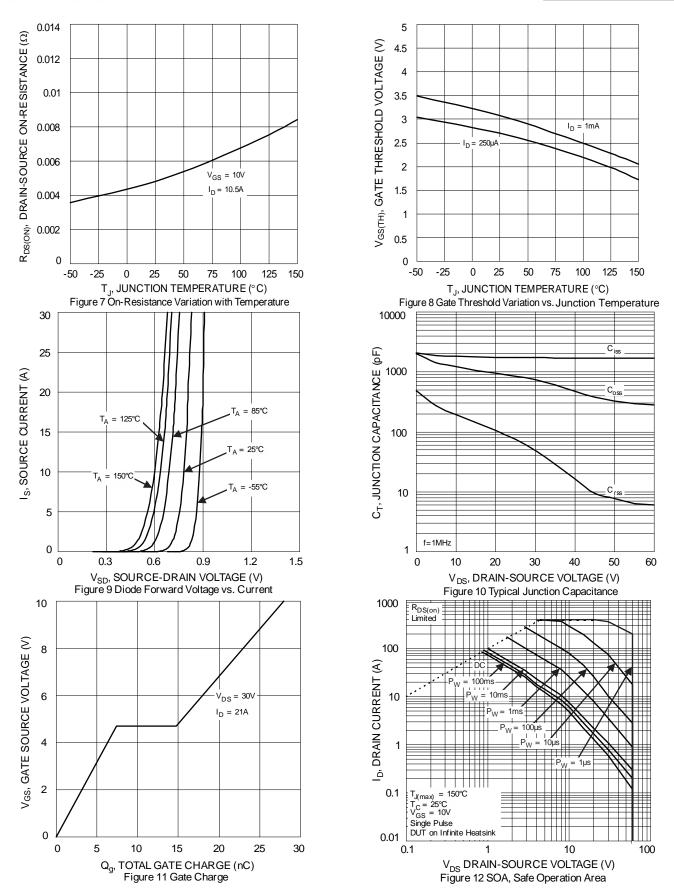
Notes:

- 5. Device mounted on FR-4 substrate PCB, 2oz copper, with 1inch square copper plate.
- 6. Thermal resistance from junction to soldering point (on the exposed drain pad).
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to product testing.











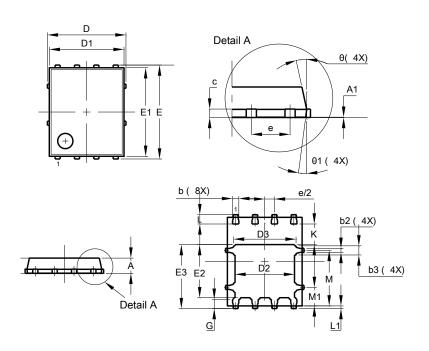




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8

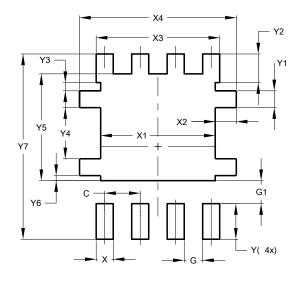


PowerDI5060-8					
Dim	Min	Тур			
Α	0.90	0.90 1.10			
A1	0.00	_			
b	0.33	0.51	0.41		
b2	0.200	0.350	0.273		
b3	0.40	0.80	0.60		
C	0.230	0.330	0.277		
D	5.15 BSC				
D1	4.70	5.10	4.90		
D2	3.70	4.10	3.90		
D3	3.90 4.30 4.10				
Е	6.15 BSC				
E1	5.60	5.60 6.00			
E2	3.28	3.68	3.48		
E3	3.99 4.39 4.19		4.19		
е	1.27 BSC				
G	0.51	0.71	0.61		
K	0.51	-	_		
L	0.51	0.71	0.61		
L1	0.100	0.200	0.175		
М	3.235	4.035	3.635		
M1	1.00	1.40	1.21		
Θ	10°	12°	11°		
Θ1	6°	8°	7°		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8



Dimensions	Value (in mm)			
С	1.270			
G	0.660			
G1	0.820			
X	0.610			
X1	4.100			
X2	0.755			
Х3	4.420			
X4	5.610			
Y	1.270			
Y1	0.600			
Y2	1.020			
Y3	0.295			
Y4	1.825			
Y5	3.810			
Y6	0.180			
Y7	6.610			



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